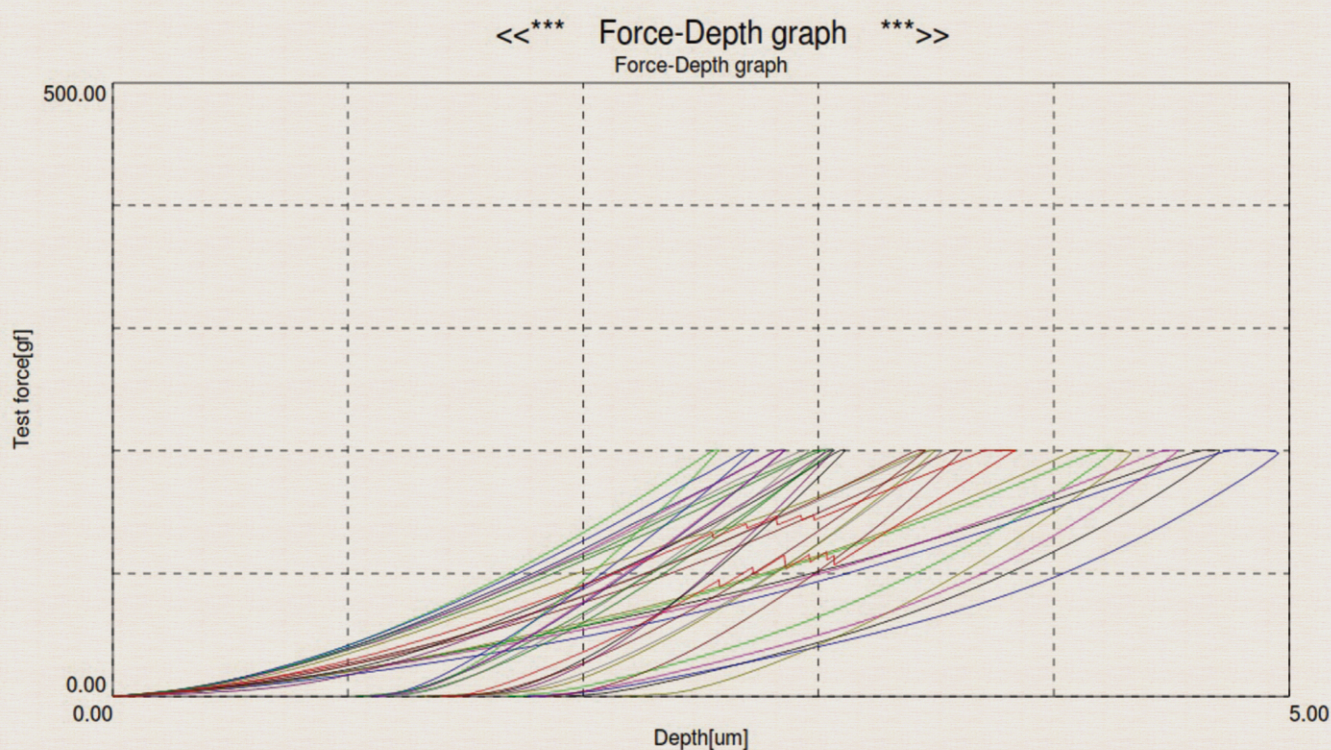


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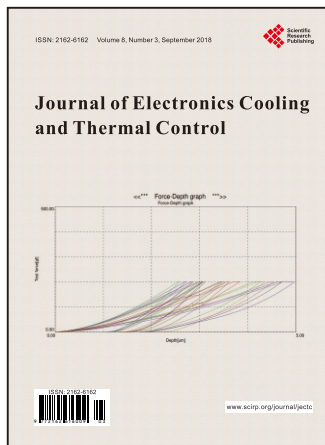
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Journal of Electronics Cooling and Thermal Control (JECTC) is a quarterly, peer-reviewed, academic journal. It aims to provide a vehicle for the exchange and dissemination of original research results, technical notes, and state-of-the-art reviews pertaining to the electronic cooling and thermal system control technology in the computer and electronics industries.

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- Phase changing heat transfer
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- Radiation
- Spray cooling
- Temperature stability
- Thermal modeling of electronics systems and components

Technologies based on these transport processes such as

- Enhanced heat/mass transfer in precision-, micro-electronics, information technology
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